nexperia

Product Change Notification CN-202511017F

Issue date: 30 Dec 2025

Effective date: 01 Apr 2026

Dear L Vidhya,

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.

Introduction of Cu-wire bonding process for leadless MicroPak packages (SOT833-1115-1116-1203) at ATSN

Change Category

[ ] Wafer Fab Process
[ ] Wafer Fab Materials
[ ] Wafer Fab Location
[X] Assembly Process
[X] Assembly Materials
[ ] Assembly Location
[ ] Product Marking
[ ] Mechanical Specification
[ ] Packing/Shipping /Labeling
[X] Test Location
[ ] Test Process
[ ] Test Equipment
[ ] Design
[ ] Errata
[ ] Electrical spec./Test coverage

Details of this change

Introduction of Cu-wire bonding process for leadless MicroPak packages (SOT833-1115-1116-1203) at ATSN (Nexperia Semiconductors Assembly & Test Plant Seremban Malaysia)

- Replace Au (gold) wire with Cu (copper) wire in bonding process
- Include ATSN as wafer test location
- No assembly location change
- No diffusion fab location change
- No wafer fab process change

No change in form, fit, function, quality, workability and reliability anticipated
No impact on the product's functionality anticipated
No change in data sheet and test limits
- No change in ordering code 12NC (sales part number)
- See also previous PCN announced by CN-202504017F which has the same subject

SQR_PCN_CN-202511017F.pdf: https://qcm.nexperia.com/Document/DOC-606173/SQR_PCN_CN-202511017F.pdf

Why do we implement this change?

- Last phase Cu-wire implementation after maturation since 2012
- Continued alignment with world technology trends on state of the art production tools
- Copper wire shows enhanced mechanical properties
- To achieve zero delamination
- Increased environmental friendliness (eco-friendly)

Identification of affected products

Change can be identified by backward traceability of the product marking date code

Management summary

Replace Au (gold) wire with Cu (copper) wire in bonding process for leadless MicroPak packages (SOT833-1115-1116-1203) at ATSN (Nexperia Semiconductors Assembly & Test Plant Seremban Malaysia)

Product availability

Production

Planned first shipment: 01 Apr 2026

Existing inventory will be shipped until depleted

Sample information

Samples are available upon request

Impact

No impact to the product's functionality anticipated

Data sheet revision

No impact to existing datasheet

Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 29 Jan 2026. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Additional information

View Change Notification Online

Remarks

PCN qualification samples are available upon request via Helpdesk+ from BG IC Solutions sample store in Nijmegen, the Netherlands. Maximum sample order 300 pieces per type

Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact you distribution partner.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.